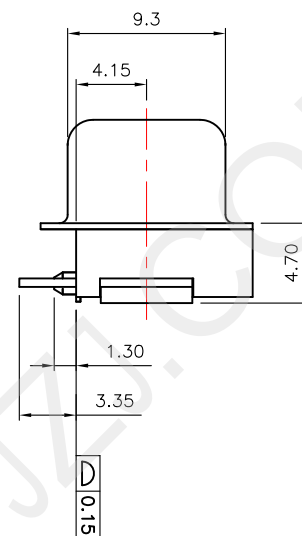
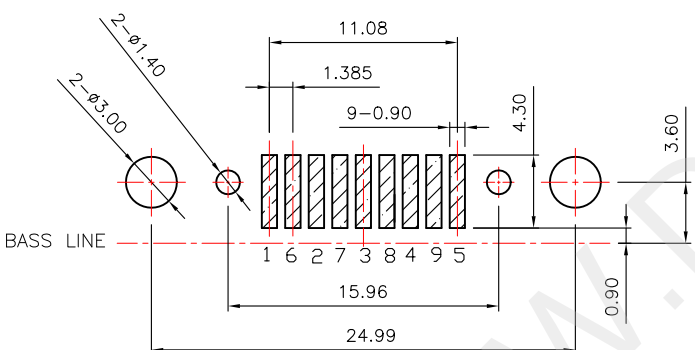
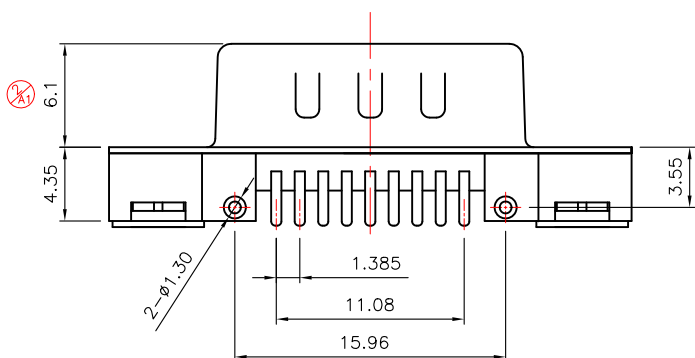
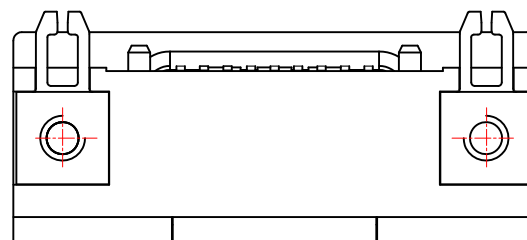
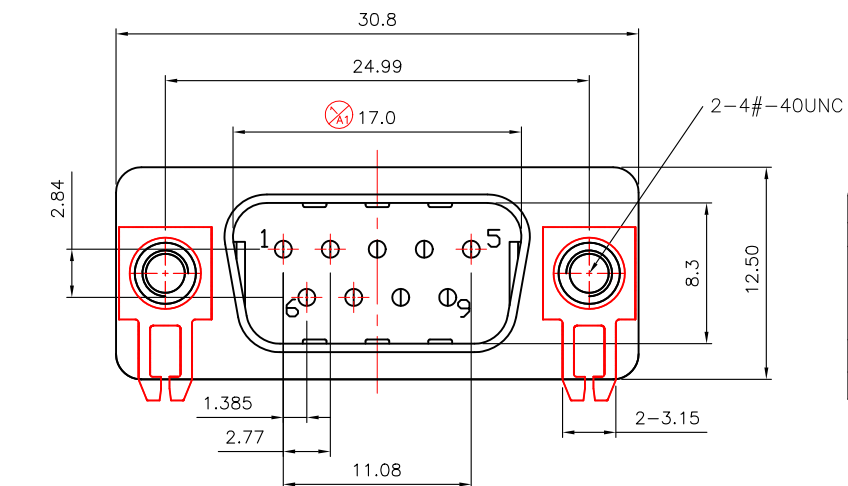




1. MATERIAL&PLATING:

- 1.1 INSULATOR AND COVER: LCP, UL94V-0
INSULATOR AND COVER COLOR: BLACK.
- 1.2 CONTACT: COPPER ALLOY, T: 0.25mm,
GOLD FLASH PLATED IN CONTACT AREA,
100u" MIN MATTE TIN PLATED IN SOLDER AREA,
30u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 SHELL: SPCC, T:0.35mm, 30u" MIN. NICKEL PLATED OVERALL.
- 1.4 BOARD LOCK: SPCC, T:0.5mm, 100u" MIN TIN PLATED OVER.
30u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.5 RIVET: COPPER ALLOY, 30u" MIN. NICKEL PLATED OVERALL.

2. SPECIFICATION:

- 2.1 CURRENT RATING: 5.0A.
- 2.2 CONTACT RESISTANCE: 30mΩ MAX.
- 2.3 INSULATION RESISTANCE: 1000MΩ Min.
- 2.4 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC PER MINUTE.

3. NOTES:

- 3.1 ALL COMPONENTS ARE RoHS COMPLIANT.
- 3.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 10 SECONDS.

RECOMMENDED P.C.B LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: D-SUB 9P公座 SMT 沉板式	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC216-VGA09A-080	
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO: HYC-2403201003	
			SHEET NO.	1 OF 1